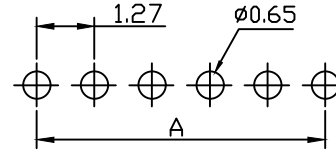
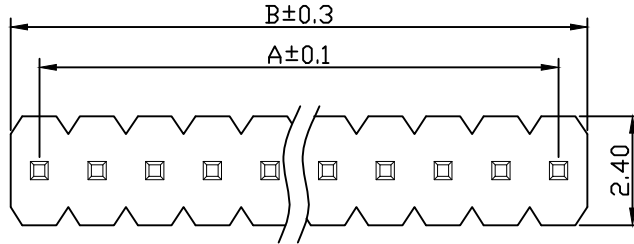


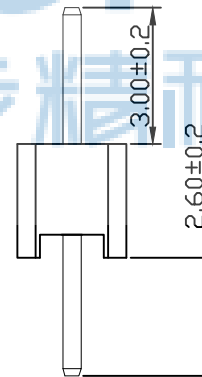
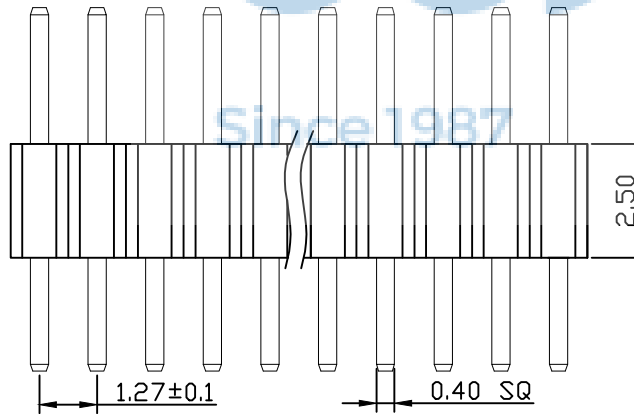
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

SPECIFICATIONS

Current Rating: 1.0 Amps
 Withstanding Voltage: AC 500V
 Insulation Resistance: 1000M Ω Min
 Contact Resistance: 20m Ω Max
 Operation Temperature: -40° to +105°
 Insulator Material: Polyester (UL94V-0)
 Contact Material: Brass
 Standard: PA6T
 Contact Plating: Gold Flash
 Max. Processing Temp: 240° C for 30-60 seconds
 (260° C for 5 seconds)



RECOMMEND P. C. B LAYOUT
 PCB TOLERANCE: ± 0.05 (TOP VIEW)



No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B
1	—	—	11	12.70	13.97	21	25.40	26.67	31	38.10	39.37	41	50.80	52.07
2	1.27	2.54	12	13.97	15.24	22	26.67	27.94	32	39.37	40.64	42	52.07	53.34
3	2.54	3.81	13	15.24	16.51	23	27.94	29.21	33	40.64	41.91	43	53.34	54.61
4	3.81	5.08	14	16.51	17.78	24	29.21	30.48	34	41.91	43.18	44	54.61	55.88
5	5.08	6.35	15	17.78	19.05	25	30.48	31.75	35	43.18	44.45	45	55.88	57.15
6	6.35	7.62	16	19.05	20.32	26	31.75	33.02	36	44.45	45.72	46	57.15	58.42
7	7.62	8.89	17	20.32	21.59	27	33.02	34.29	37	45.72	46.99	47	58.42	59.69
8	8.89	10.16	18	21.59	22.86	28	34.29	35.56	38	46.99	48.26	48	59.69	60.96
9	10.16	11.43	19	22.86	24.13	29	35.56	36.83	39	48.26	49.53	49	60.96	62.23
10	11.43	12.70	20	24.13	25.40	30	36.83	38.10	40	49.53	50.80	50	62.23	63.50



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司		NAME: 排针 1.27PH H2.5 1x10P 180度 PC2.6 PA3.0 PB2.5 L8.1 6T 0.4针	
APPD. JM_Zheng CHKD. LYX DR. SGF		.X: ± 0.38 .X*: $\pm 3'$.XX: ± 0.25 .X*: $\pm 2'$.XXX: ± 0.13 .X*: $\pm 1'$		PJ. NO.: PH.03.11-41-6004 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/1	